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U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office
SHEET

Attorney Docket No.: 040894-7166

To the Commissioner for Patents

ATTN: MAIL STOP ASSIGNMENT RECORDATION SERVICES

Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

1. Yongxun LIU
2. Toshihiro SEKIGAWA
3. Meishoku MASAHARA
4. Kenichi ISHII
5. Eiichi SUZUKI

Additional names of conveying party(ies) attached?

☐ Yes ☒ No

2. Name and address of receiving party(ies):

Name: NATIONAL INSTITUTE OF ADVANCED
INDUSTRIAL SCIENCE AND TECHNOLOGY

Internal Address:

Street Address: 3-1, Kasumigaseki 1-chome,
Chiyoda-ku, Tokyo 100-8921 Japan

City:

State:

Zip:

Additional name(s) & address(es) attached?

☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution Date: (1-5) February 21, 2005

4. New Application number(s) or patent number(s): **NEW APPLICATION**

If this document is being filed together with a new application the execution date of the application is:

(1-5) February 21, 2005

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached: ☐ Yes ☒ No

5. Name and address of party to whom correspondence
concerning document should be mailed:

Name: **Robert J. Gaybrick**

Internal Address: Morgan, Lewis & Bockius LLP
Customer No. 09629

Street Address: 1111 Pennsylvania Ave., N.W.

City: Washington State: D.C. Zip: 20004

6. Total number of applications and patents involved: 1

7. Total fee (37 C.F.R. §3.41): \$40.00

☐ Enclosed

☒ Authorized to be charged to Deposit Account 50-0310

8. Deposit Account No. 50-0310

(Attach duplicate page if paying by deposit account)

9. Statement and Signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Robert J. Goodell, Reg. #41,040

Name of Person Signing

Signature

March 1, 2005

Date

Total number of pages including cover sheet, attachments and documents: 3

03/15/2005 ECOOPER 00000189 500310 11067699

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PATENT
REEL: 016355 FRAME: 0032

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:
SEMICONDUCTOR INTEGRATED CIRCUIT AND METHOD FOR MANUFACTURING THE SAME

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on _____, (Application No. _____); and

WHEREAS, * see below _____, a corporation of Japan _____, whose post office address is _____
** see below (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. _____, filed March 1, 2005) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

Full Name of Sole or First Assignor Yongxun LIU	Assignor's Signature <i>Yongxun Liu</i>	Date February 21, 2005
Address Ibaraki, Japan		Citizenship China
Full Name of Second Assignor Toshihiro SEKIGAWA	Assignor's Signature <i>Toshihiro Sekigawa</i>	Date February 21, 2005
Address Ibaraki, Japan		Citizenship Japan
Names of additional inventors attached <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No		

* National Institute of Advanced Industrial Science and Technology

** 3-1, Kasumigaseki 1-chome, Chiyoda-ku, Tokyo 100-8921 Japan

Full Name of Third Assignor Meishoku MASAHARA	Assignor's Signature 昌原明植	Date February 21, 2005
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Full Name of Fourth Assignor Kenichi ISHII	Assignor's Signature Kenichi Ishii	Date February 21, 2005
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Full Name of Fifth Assignor Eiichi SUZUKI	Assignor's Signature Eiichi Suzuki	Date February 21, 2005
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Address		Citizenship
Full Name of Seventh Assignor	Assignor's Signature	Date
Address		Citizenship
Full Name of Eighth Assignor	Assignor's Signature	Date
Address		Citizenship
Full Name of Ninth Assignor	Assignor's Signature	Date
Address		Citizenship
Full Name of Tenth Assignor	Assignor's Signature	Date
Address		Citizenship
Full Name of Eleventh Assignor	Assignor's Signature	Date
Address		Citizenship
Names of additional inventors attached		<input type="checkbox"/> Yes <input checked="" type="checkbox"/> No